

35. (Amended) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the single connection component is formed having a male shape.

36. (Amended) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the single connection component is formed having a female shape.

C1 37. (Amended) The method of making a dielectric package for housing a component and having an integral connection component of claim 36, further comprising:

coupling a component to said first die prior to bonding the second die to said first die.

38. (Amended) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, further comprising:

etching an aperture into said second die.

39. (Amended) The method of making a dielectric package for housing a component and having an integral connection component of claim 38, wherein a component is placed through said aperture on said second die and coupled to said first die after the second die is bonded to the first die.

40 (Amended) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the component is an integrated circuit.

41. (Amended) The method of making a dielectric package for housing a component and having an integral connection component of claim 40, wherein the integrated circuit is a millimeter microwave integrated circuit.

C' 42. (Amended) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the component is an optical fiber.

43. (Amended) The method of making a dielectric package for housing a component and having an integral connection component of claim 34, wherein the component is an optical semiconductor.

Please add the following new claims

C2 44. The method of making a dielectric package for housing a component and having an integral connection member of claim 34, wherein the dielectric package has a plurality of connection components.

45. The method of making a dielectric package for housing a component and having an integral connection member of claim 44, wherein the dielectric package having plurality of connection components includes both female and male shaped connection components.
